

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc2226hlx#pbf

(Engineering Calculation)

LQFP 7mm X 7mm

(printed on: 2020-07-11 19:27:43)

**TOTAL MASS (g) : 0.192861**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003752	1000000	19454.3945312		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.042592	693000	220842.65625		
		Iron (Fe)	7439-89-6	0.000651	10599.9990234	3375.48291016		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000602	9800	3121.41430664		
		Nickel (Ni)	7440-02-0	0.013288	216200.015625	68899.2578125		
		Silicon (Si)	7440-21-3	0.000369	25400	8093.89990234		
		Magnesium (Mg)	7439-95-4	0.001561	25400	8093.89990234		
		Tin (Sn)	7440-31-5	0.002397	39000	12428.6220703		
<b>Lead Frame Total:</b>				<b>0.061460</b>	<b>1000000</b>	<b>318674.625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002712	1000000	14063.4511719		
		<b>External Plating Total:</b>				<b>0.002712</b>	<b>1000000</b>	<b>14063.4511719</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001274	1000000	6605.78417969		
<b>Internal Plating Total:</b>				<b>0.001274</b>	<b>1000000</b>	<b>6605.78417969</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000439	750000	2276.24731445		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000146	250000	757.020751953		
<b>Die Attach Total:</b>				<b>0.000585</b>	<b>1000000</b>	<b>3033.26806641</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.015015	123000	77853.8828125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.106689	874000	553190.375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000366	3000	1897.73693848		
		<b>Encapsulation Total:</b>				<b>0.122070</b>	<b>1000000</b>	<b>632941.9375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001008	1000000	5226.55419922		
					<b>TOTAL MASS (g) :</b>	<b>0.192861</b>		